

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				Complete if Known		
				Application Number		Not Yet Assigned
				Filing Date		June 23, 2003
				First Named Inventor		Mitsuru SEKIGUCHI
				Art Unit		2813
				Examiner Name		Not Yet Assigned
Sheet	1	of	1	Attorney Docket Number		740819-1014

U.S. PATENT DOCUMENTS						
Examiner Initials ¹	Cite No. ¹	U.S. Patent Document		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)				
		US-6,181,012 B1		01/30/2001	Edelstein et al	
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FOREIGN PATENT DOCUMENTS							
Examiner Initials ¹	Cite No. ¹	Foreign Patent Document		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁴
		Country Code ³ Number ⁴	Kind Code ² (if known)				
		JP 02-114639 A		04/26/1990	Seiichi		W/Abstract

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
Examiner Initials ¹	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ⁵
		P.J. Ding et al., "Oxidation resistant high conductivity copper films", Appl. Phys. Lett. 64, No. 21, pp. 2897-2899, May 23, 1994	
		C Ryu et al., "Effect of Texture on the Electromigration of CVD Copper", IEEE, pp. 201-205, 1997	
		M. Hasunuma et al., "Copper Reflow Process With Redox Cycle Reaction", The 42 nd Spring Meeting of the Japan Society of Applied Physics, No. 2, p. 810, 30a-K-6, March 1995, with English Translation	
Examiner Signature			Date Considered 3/17/04

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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